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FDN352AP Single P-Channel, PowerTrench® MOSFET

Features

- -1.3 A, -30V $R_{DS(ON)} = 180 \text{ m}\Omega$ @ $V_{GS} = -10V$ -1.1 A, -30V $R_{DS(ON)} = 300 \text{ m}\Omega$ @ $V_{GS} = -4.5V$
- High performance trench technology for extremely low R_{DS(ON)}.
- High power version of industry Standard SOT-23 package. Identical pin-out to SOT-23 with 30% higher power handling capability.

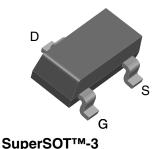
Applications

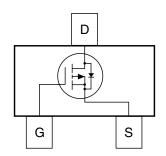
■ Notebook computer power management

General Description

This P-Channel Logic Level MOSFET is produced using Fairchild Semiconductor advanced Power Trench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance

These devices are well suited for low voltage and battery powered applications where low in-line power loss is needed in a very small outline surface mount package.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-30	V
V _{GSS}	Gate-Source Voltage		±25	V
I _D	Drain Current - Continuous	(Note 1a)	-1.3	Α
	- Pulsed		-10	
P _D	Power Dissipation for Single Operation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C
Thermal Cha	aracteristics			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)		75	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
52AP	FDN352AP	7"	8mm	3000 units

Electrical Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units		
Off Charac	Off Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30			V		
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		-17		mV/°C		
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μА		
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA		
On Charac	cteristics (Note 2)			•				
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.8	-2.0	-2.5	V		
$\frac{\Delta V_{\text{GS(th)}}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$, Referenced to 25°C		4		mV/°C		
R _{DS(on)}	Static Drain–Source On–Resistance	$V_{GS} = -10 \text{ V}, I_D = -1.3 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -1.1 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -1.1 \text{ A}, T_J = 125^{\circ}\text{C}$		150 250 330	180 300 400	mΩ		
9 _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, I_{D} = -0.9 \text{ A}$		2.0		S		
Dynamic C	Characteristics							
C _{iss}	Input Capacitance	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$		150		pF		
C _{oss}	Output Capacitance			40		pF		
C _{rss}	Reverse Transfer Capacitance	1		20		pF		
Switching	Characteristics (Note 2)			•	•			
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -10 \text{ V}, I_D = -1 \text{ A},$		4	8	ns		
t _r	Turn-On Rise Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$		15	28	ns		
t _{d(off)}	Turn-Off Delay Time			10	18	ns		
t _f	Turn-Off Fall Time			1	2	ns		
Qg	Total Gate Charge	$V_{DS} = -10V$, $I_D = -0.9$ A,		1.4	1.9	nC		
Q _{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$		0.5		nC		
Q _{gd}	Gate-Drain Charge			0.5		nC		
Drain-Sou	irce Diode Characteristics and Maximum Ra	tings						
I _S	Maximum Continuous Drain-Source Diode Fo	orward Current			-0.42	Α		
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -0.42 \text{ A}$ (Note 2)		-0.8	-1.2	V		
t _{rr}	Diode Reverse Recovery Time	$I_F = -3.9 \text{ A},$		17		ns		
Q _{rr}	Diode Reverse Recovery Charge	dl _F /dt = 100 A/μs		7		nC		

Notes:

1. R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins R_{0,JC} is guaranteed by design while R_{0,JA} is determined by the user's board design.

⁽a) $R_{\theta JA} = 250^{\circ}C/W$ when mounted on a 0.02 in² pad of 2oz. copper.

⁽b) $R_{\theta JA}$ = 270°C/W when mounted on a 0.001 in² pad of 2oz. copper.

^{2.} Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Typical Characteristics

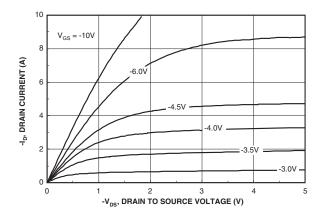


Figure 1. On-Region Characteristics.

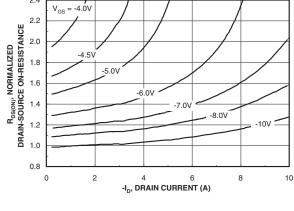


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

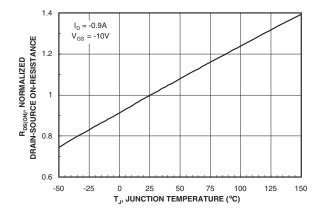


Figure 3. On-Resistance Variation with Temperature.

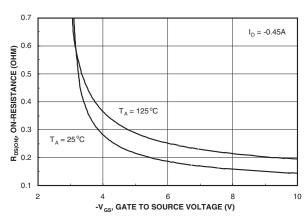


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

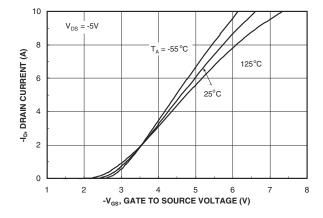


Figure 5. Transfer Characteristics.

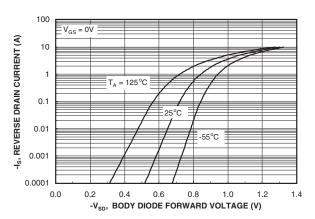
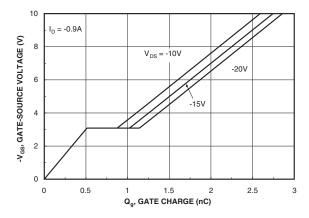


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



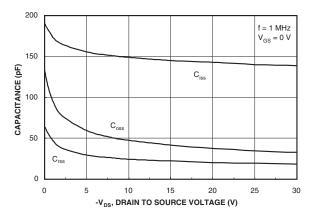
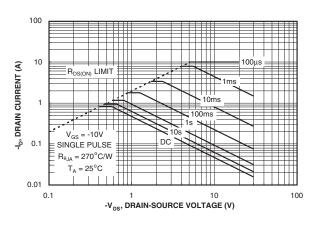


Figure 7. Gate Charge Characteristics.





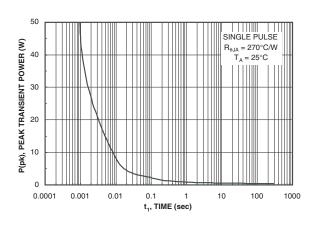


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

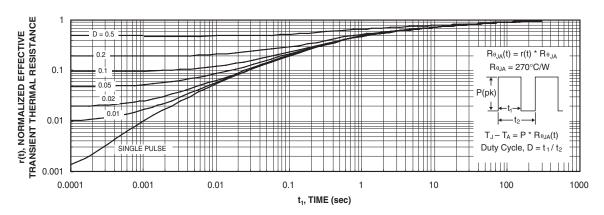


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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